

TinyLogic UHS Unbuffered Inverter

NC7SZU04

Description

The NC7SZU04 is a single unbuffered inverter from ON Semiconductor's Ultra-High Speed series of TinyLogic. The special purpose unbuffered circuit design is primarily intended for crystal oscillator or analog applications. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} range.

Features

- Unbuffered for Crystal Oscillator and Analog Applications
- Balanced Output Drive: ± 32 mA at 4.5 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches Performance of LCX Operated at 3.3 V V_{CC}
- Low Quiescent Power: $I_{CC} < 2 \mu A$, $V_{CC} = 5.5$ V, $T_A = 25^\circ C$
- Ultra-Small MicroPak™ Packages
- Space-Saving SC-74A and SC-88A Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

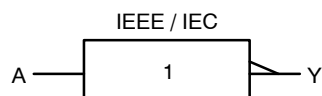


Figure 1. Logic Symbol



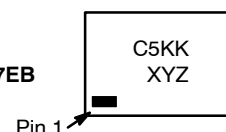
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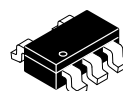
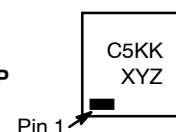
MARKING DIAGRAMS



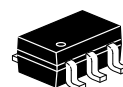
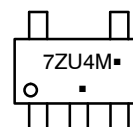
SIP6
CASE 127EB



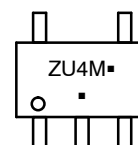
UDFN6
CASE 517DP



SC-74A
CASE 318BQ



SC-88A
CASE 419A-02



C5, 7ZU4, ZU4 = Specific Device Code
 KK = 2-Digit Lot Run Traceability Code
 XY = 2-Digit Date Code Format
 Z = Assembly Plant Code
 M = Date Code*
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NC7SZU04

Pin Configurations

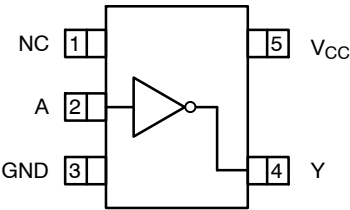


Figure 2. SC88A and SC-74A (Top View)

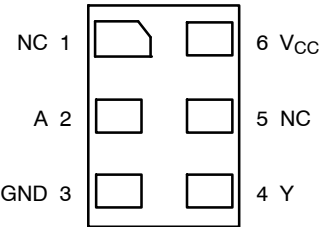


Figure 3. MicroPak (Top Through View)

PIN DEFINITIONS

Pin # SC-88A / SC74A	Pin # MicroPak	Name	Description
1	1, 5	NC	No Connect
2	2	A	Input
3	3	GND	Ground
4	4	Y	Output
5	6	V _{CC}	Supply Voltage

FUNCTION TABLE

Inputs	Output
A	Y
L	H
H	L

H = HIGH Logic Level
L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Supply Voltage		−0.5	6.5	V
V _{IN}	DC Input Voltage		−0.5	6.5	V
V _{OUT}	DC Output Voltage		−0.5	V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	−	−50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	−	−50	mA
		V _{OUT} > V _{CC}	−	+50	
I _{OUT}	DC Output Current		−	±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current		−	±50	mA
T _{STG}	Storage Temperature Range		−65	+150	°C
T _J	Junction Temperature Under Bias		−	+150	°C
T _L	Junction Lead Temperature (Soldering, 10 Seconds)		−	+260	°C
P _D	Power Dissipation in Still Air	SC−74A	−	390	mW
		SC−88A	−	332	
		MicroPak−6	−	812	
		MicroPak2™−6	−	812	
ESD	Human Body Model, JEDEC: JESD22−A114		−	4000	V
	Charge Device Model, JEDEC: JESD22−C101		−	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Retention		1.50	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		−40	+85	°C
θ _{JA}	Thermal Resistance	SC−74A	−	320	°C/W
		SC−88A	−	377	
		MicroPak−6	−	154	
		MicroPak2−6	−	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

NC7SZU04

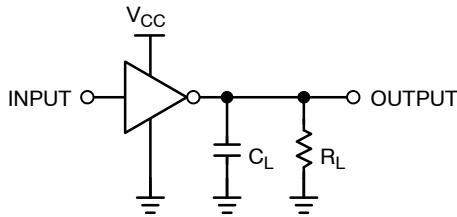
DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	HIGH Level Input Voltage		1.8 to 2.7	0.85 V _{CC}	–	–	0.85 V _{CC}	–	V
			3.0 to 5.5	0.80 V _{CC}	–	–	0.80 V _{CC}	–	
V _{IL}	LOW Level Input Voltage		1.8 to 2.7	–	–	0.15 V _{CC}	–	0.15 V _{CC}	V
			3.0 to 5.5	–	–	0.20 V _{CC}	–	0.20 V _{CC}	
V _{OH}	High-Level Output Voltage	V _{IN} = GND							V
		I _{OH} = –100 µA	1.65 to 5.5	V _{CC} – 0.1	V _{CC}	–	V _{CC} – 0.1	–	
		I _{OH} = –4 mA	1.65	1.29	1.4	–	1.29	–	
		I _{OH} = –8 mA	2.3	1.9	2.1	–	1.9	–	
		I _{OH} = –12 mA	2.7	2.2	2.4	–	2.2	–	
		I _{OH} = –16 mA	3.0	2.4	2.7	–	2.4	–	
		I _{OH} = –24 mA	3.0	2.3	2.5	–	2.3	–	
V _{OL}	Low-Level Output Voltage	I _{OH} = –32 mA	4.5	3.8	4.0	–	3.8	–	V
		V _{IN} = V _{CC}							
		I _{OL} = 100 µA	1.65 to 5.5	–	–	0.1	–	0.1	
		I _{OL} = 4 mA	1.65	–	0.08	0.24	–	0.24	
		I _{OL} = 8 mA	2.3	–	0.2	0.3	–	0.3	
		I _{OL} = 12 mA	2.7	–	0.22	0.4	–	0.4	
		I _{OL} = 16 mA	3.0	–	0.28	0.4	–	0.4	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V, GND	1.65 to 5.5	–	–	±1	–	±10	µA
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V, GND	1.65 to 5.5	–	–	2	–	20	µA
I _{CCPEAK}	Peak Supply Current in Analog Operation	V _{OUT} = Open, V _{IN} = Adjust for Peak I _{CC} Current	1.8	–	2	–	–	–	mA
			2.5	–	4	–	–	–	
			3.3	–	10	–	–	–	
			5.0	–	30	–	–	–	

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay (Figure 4, 5)	1.65	C _L = 15 pF, R _L = 1 MΩ	–	–	11.7	–	12.1	ns
		1.80		–	–	8.5	–	9.0	
		2.50 ±0.20		–	–	6.2	–	6.5	
		3.30 ±0.30		–	–	4.5	–	4.8	
		5.00 ±0.50		–	–	3.9	–	4.1	
		3.30 ±0.30	C _L = 50 pF, R _L = 500 Ω	–	–	6.0	–	6.5	
		5.00 ±0.50		–	–	5.0	–	5.5	
C _{IN}	Input Capacitance	0.00		–	4.5	–	–	–	pF
C _{PD}	Power Dissipation Capacitance (Note 2) (Figure 6)	3.30		–	6.3	–	–	–	pF
		5.00		–	9.5	–	–	–	

2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression:
 $I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CCstatic})$.



- NOTE:
 3. C_L includes load and stray capacitance.
 4. Input PRR = 1.0 MHz; t_W = 500 ns

Figure 4. AC Test Circuit

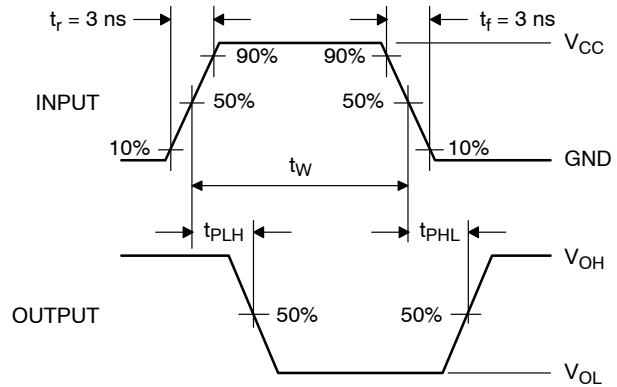
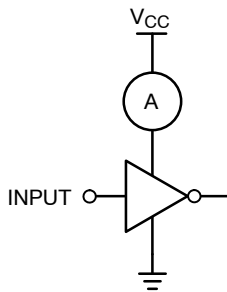


Figure 5. AC Waveforms



- NOTE:
 5. When operating the NC7SZU04's unbuffered output stage in its linear range, as in oscillator applications, care must be taken to observe maximum power rating for the device and package. The high drive nature of the design of the output stage results in substantial simultaneous conduction currents when the stage is in the linear region. See the I_{CCPEAK} specification in the [DC Electrical Characteristics](#) table.
 6. Input = AC Waveform; t_r = t_f = 1.8 ns; PRR = Variable; Duty Cycle = 50%.

Figure 6. I_{CCD} Test Circuit

NC7SZU04

ORDERING INFORMATION

Part Number	Top Mark	Packages	Shipping [†]
NC7SZU04M5X	7ZU4	SC-74A	3000 / Tape & Reel
NC7SZU04P5X	ZU4	SC-88A	3000 / Tape & Reel
NC7SZU04L6X	C5	SIP6, MicroPak	5000 / Tape & Reel
NC7SZU04FHX	C5	UDFN6, MicroPak2	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

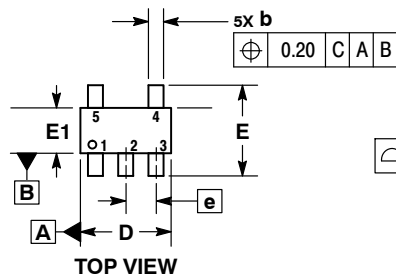
ON Semiconductor®



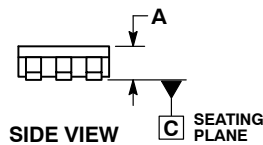
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SC-74A CASE 318BQ ISSUE B

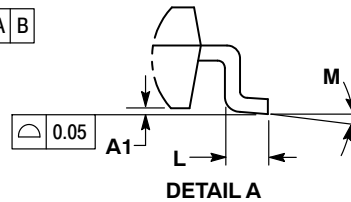
DATE 18 JAN 2018



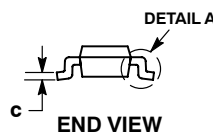
TOP VIEW



SIDE VIEW



DETAIL A



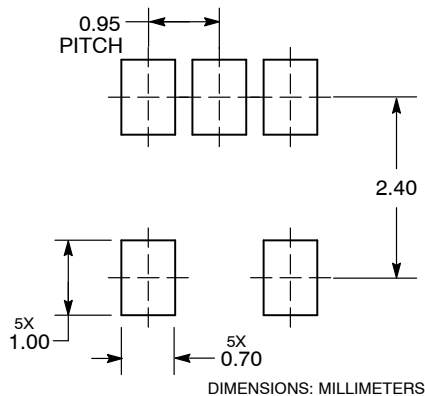
END VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

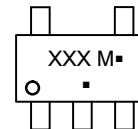
DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0°	10°

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

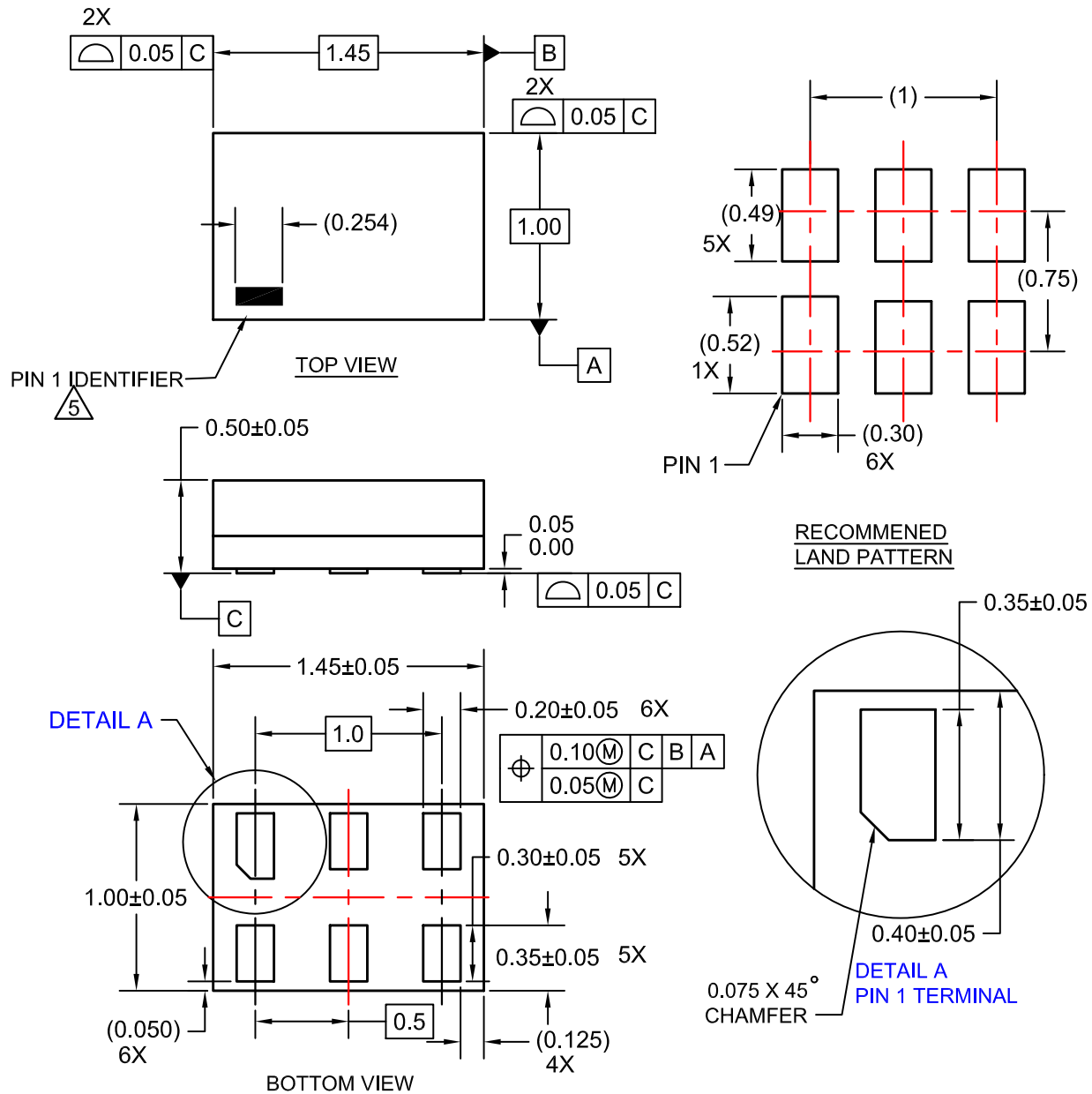
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ON

DATE 31 AUG 2016



NOTES:

1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-2009
4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

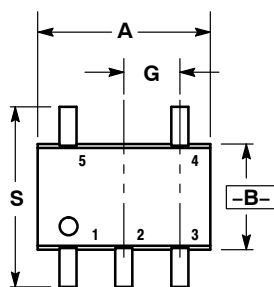
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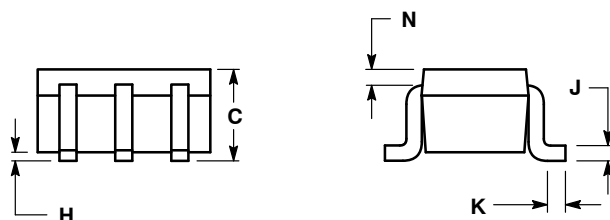
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SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE L

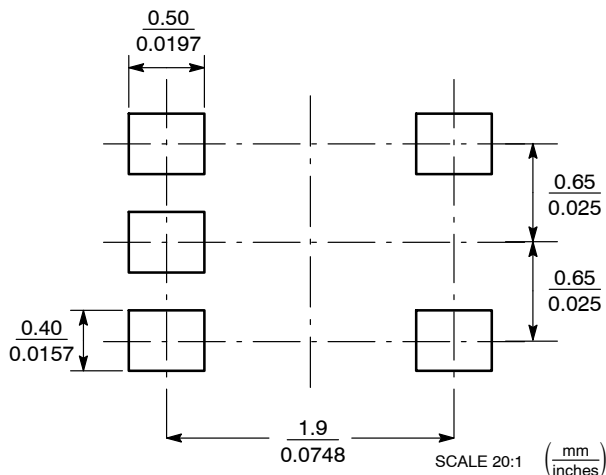
DATE 17 JAN 2013



D 5 PL $\oplus$ 0.2 (0.008) (M) B (M)



SOLDER FOOTPRINT



STYLE 1:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 3:
PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 6:
PIN 1. EMITTER 2
2. BASE 2
3. EMITTER 1
4. COLLECTOR
5. COLLECTOR 2/BASE 1

STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8:
PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

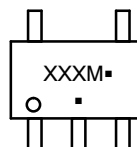
Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- 419A-01 OBSOLETE. NEW STANDARD 419A-02.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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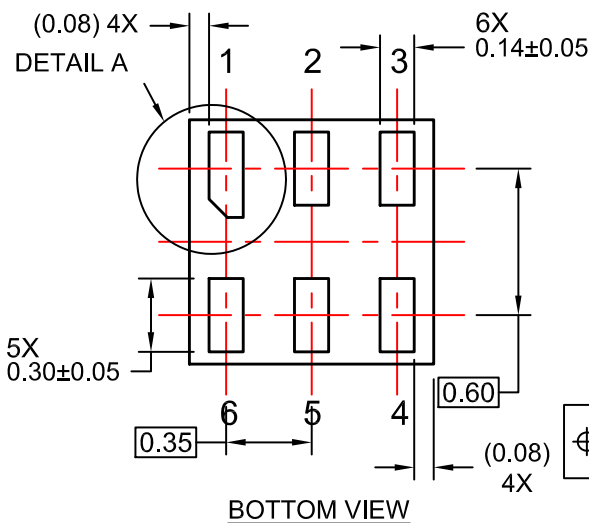
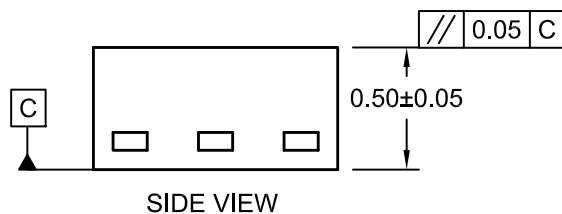
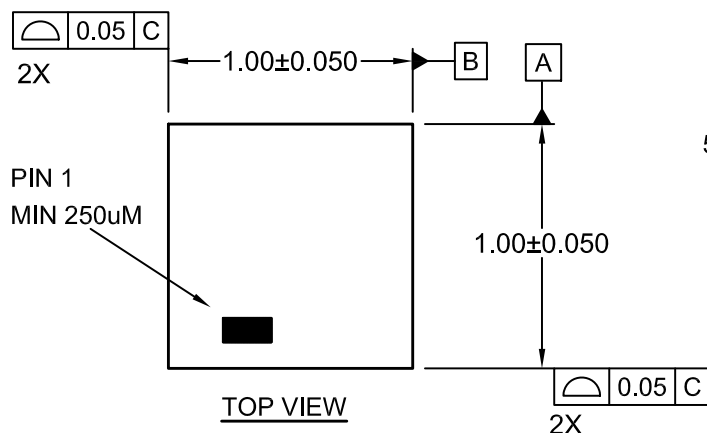
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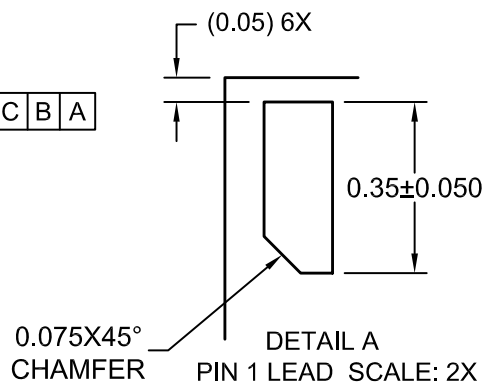
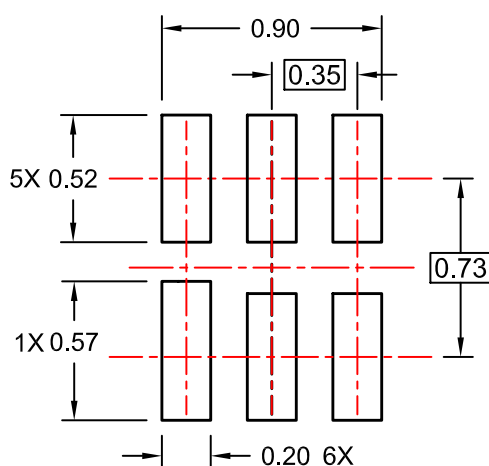
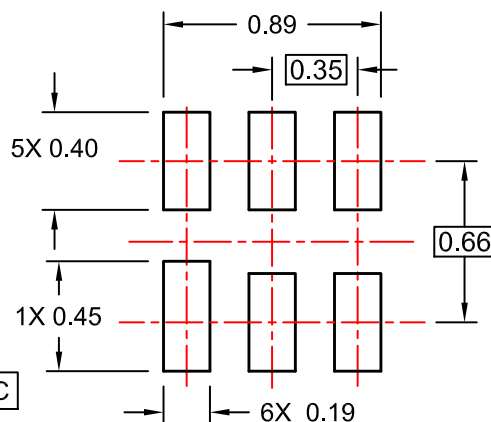
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CASE 517DP
ISSUE O

DATE 31 AUG 2016



NOTES:

- A. COMPLIES TO JEDEC MO-252 STANDARD
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009



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